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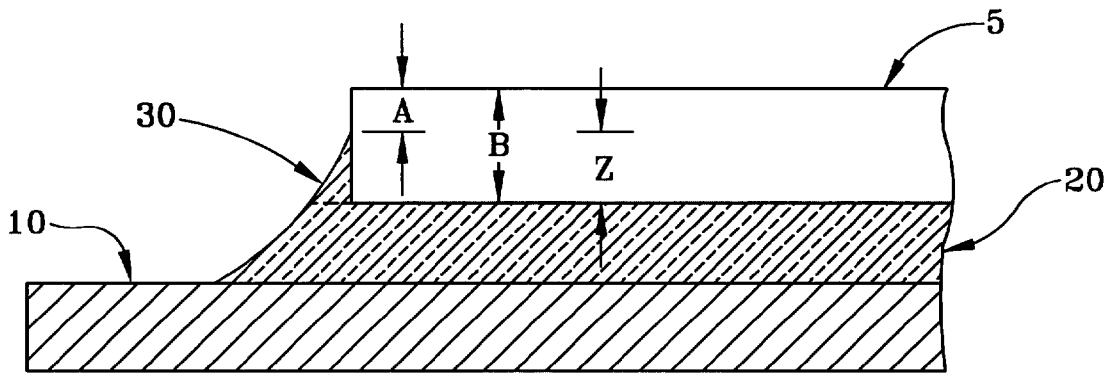
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(54) Title: METHOD AND APPARATUS FOR CONTROLLING DIE ATTACH FILLET HEIGHT TO REDUCE DIE SHEAR STRESS




(57) Abstract: A method and an apparatus for preventing cracking and delamination in a packaged semiconductor chip by controlling the die attach fillet (30) height (Z). Specifically, the present invention controls the die attach material(20) height, thereby controlling the die attach fillet (30) height (Z), and thereby reducing shear stress in the die (5) itself. Advantages of the present invention include increasing wire-bond reliability and package reliability without the need for requalification of existing products. By using currently qualified molding compounds and die attach epoxies in conjunction with the present technique for controlling the die attach epoxy height in order to control the die attach fillet (30) height (Z), the overall assembly process may be maintained. Thus, neither thermal performance nor electrical performance is compromised.

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